Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	516096
Number of I/O	620
Number of Gates	3000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TJ)
Package / Case	896-BGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a3pe3000l-1fg896m

1 – Military ProASIC3/EL Device Family Overview

General Description

The military ProASIC3/EL family of flash FPGAs dramatically reduces dynamic power consumption by 40% and static power by 50%. These power savings are coupled with performance, density, true single chip, 1.2 V to 1.5 V core and I/O operation, reprogrammability, and advanced features.

Microsemi's proven Flash*Freeze technology enables military ProASIC3EL device users to shut off dynamic power instantaneously and switch the device to static mode without the need to switch off clocks or power supplies, and retaining internal states of the device. This greatly simplifies power management. In addition, optimized software tools using power-driven layout provide instant push-button power reduction.

Nonvolatile flash technology gives military ProASIC3/EL devices the advantage of being a secure, low-power, single-chip solution that is live at power-up (LAPU). Military ProASIC3/EL devices offer dramatic dynamic power savings, giving FPGA users flexibility to combine low power with high performance.

These features enable designers to create high-density systems using existing ASIC or FPGA design flows and tools.

Military ProASIC3/EL devices offer 1 kbit of on-chip, reprogrammable, nonvolatile FlashROM storage as well as clock conditioning circuitry (CCC) based on an integrated phase-locked loop (PLL). Military ProASIC3/EL devices support devices from 250K system gates to 3 million system gates with up to 504 kbits of true dual-port SRAM and 620 user I/Os.

M1 military ProASIC3/EL devices support the high-performance, 32-bit Cortex-M1 processor developed by ARM for implementation in FPGAs. ARM Cortex-M1 is a soft processor that is fully implemented in the FPGA fabric. It has a three-stage pipeline that offers a good balance between low-power consumption and speed when implemented in an M1 military ProASIC3/EL device. The processor runs the ARMv6-M instruction set, has a configurable nested interrupt controller, and can be implemented with or without the debug block. ARM Cortex-M1 is available at no cost from Microsemi for use in M1 military ProASIC3/EL FPGAs.

The ARM-enabled devices have ordering numbers that begin with M1 and do not support AES decryption.

Flash*Freeze Technology†

Military ProASIC3EL devices offer Flash*Freeze technology, which allows instantaneous switching from an active state to a static state. When Flash*Freeze mode is activated, military ProASIC3EL devices enter a static state while retaining the contents of registers and SRAM. Power is conserved without the need for additional external components to turn off I/Os or clocks. Flash*Freeze technology is combined with in-system programmability, which enables users to quickly and easily upgrade and update their designs in the final stages of manufacturing or in the field. The ability of military ProASIC3EL devices to support a 1.2 V core voltage allows for an even greater reduction in power consumption, which enables low total system power.

When the military ProASIC3EL device enters Flash*Freeze mode, the device automatically shuts off the clocks and inputs to the FPGA core; when the device exits Flash*Freeze mode, all activity resumes and data is retained.

The availability of low-power modes, combined with a reprogrammable, single-chip, single-voltage solution, make military ProASIC3EL devices suitable for low-power data transfer and manipulation in military-temperature applications where available power may be limited (e.g., in battery-powered equipment); or where heat dissipation may be limited (e.g., in enclosures with no forced cooling).

---

† *Flash*Freeze technology is not supported on A3P1000.*

Flash Advantages

Low Power[ƒ]

The military ProASIC3EL family of flash-based FPGAs provides a low-power advantage, and when coupled with high performance, enables designers to make power-smart choices using a single-chip, reprogrammable, and live-at-power-up device.

Military ProASIC3EL devices offer 40% dynamic power and 50% static power savings by reducing the core operating voltage to 1.2 V. In addition, the power-driven layout (PDL) feature in Libero®SoC offers up to 30% additional power reduction. With Flash*Freeze technology, military ProASIC3EL device is able to retain device SRAM and logic while dynamic power is reduced to a minimum, without the need to stop clock or power supplies. Combining these features provides a low-power, feature-rich, and high-performance solution.

Security

Nonvolatile, flash-based military ProASIC3/EL devices do not require a boot PROM, so there is no vulnerable external bitstream that can be easily copied. Military ProASIC3/EL devices incorporate FlashLock, which provides a unique combination of reprogrammability and design security without external overhead, advantages that only an FPGA with nonvolatile flash programming can offer.

Military ProASIC3/EL devices utilize a 128-bit flash-based lock and a separate AES key to secure programmed intellectual property and configuration data. In addition, all FlashROM data in military ProASIC3/EL devices can be encrypted prior to loading, using the industry-leading AES-128 (FIPS192) bit block cipher encryption standard. AES was adopted by the National Institute of Standards and Technology (NIST) in 2000 and replaces the 1977 DES standard. Military ProASIC3/EL devices have a built-in AES decryption engine and a flash-based AES key that make them the most comprehensive programmable logic device security solution available today. Military ProASIC3/EL devices with AES-based security allow for secure, remote field updates over public networks such as the Internet, and ensure that valuable IP remains out of the hands of system overbuilders, system cloners, and IP thieves.

Security, built into the FPGA fabric, is an inherent component of the military ProASIC3/EL family. The flash cells are located beneath seven metal layers, and many device design and layout techniques have been used to make invasive attacks extremely difficult. The military ProASIC3/EL family, with FlashLock and AES security, is unique in being highly resistant to both invasive and noninvasive attacks. Your valuable IP is protected and secure, making remote ISP possible. A military ProASIC3/EL device provides the most impenetrable security for programmable logic designs.

Single Chip

Flash-based FPGAs store their configuration information in on-chip flash cells. Once programmed, the configuration data is an inherent part of the FPGA structure, and no external configuration data needs to be loaded at system power-up (unlike SRAM-based FPGAs). Therefore, flash-based military ProASIC3/EL FPGAs do not require system configuration components such as EEPROMs or microcontrollers to load device configuration data. This reduces bill-of-materials costs and PCB area, and increases security and system reliability.

Live at Power-Up

Flash-based military ProASIC3/EL devices support Level 0 of the LAPU classification standard. This feature helps in system component initialization, execution of critical tasks before the processor wakes up, setup and configuration of memory blocks, clock generation, and bus activity management. The LAPU feature of flash-based military ProASIC3/EL devices greatly simplifies total system design and reduces total system cost, often eliminating the need for CPLDs and clock generation PLLs. In addition, glitches and brownouts in system power will not corrupt the military ProASIC3/EL device's flash configuration, and unlike SRAM-based FPGAs, the device will not have to be reloaded when system power is restored. This enables the reduction or complete removal of the configuration PROM, expensive voltage monitor, brownout detection, and clock generator devices from the PCB design. Flash-based military ProASIC3/EL devices simplify total system design and reduce cost and design risk while increasing system reliability and improving system initialization time.

[ƒ] *A3P1000 only supports 1.5 V core operation.*

Table 2-2 • Recommended Operating Conditions [1]

Symbol	Parameter		Military	Units
T_J	Junction temperature		–55 to 125 [2]	°C
VCC	1.5 V DC core supply voltage[3]		1.425 to 1.575	V
	1.2 V – 1.5 V wide range DC core supply voltage [4]		1.14 to 1.575	V
VJTAG	JTAG DC voltage		1.4 to 3.6	V
VPUMP[5]	Programming voltage	Programming mode	3.15 to 3.45	V
		Operation[6]	0 to 3.6	V
VCCPLL[5]	Analog power supply (PLL)	1.5 V DC core supply voltage[3]	1.425 to 1.575	V
		1.2 V – 1.5 V DC core supply voltage[4]	1.14 to 1.575	V
VCCI and VMV[5]	1.2 V DC supply voltage[4]		1.14 to 1.26	V
	1.2 V wide range DC supply voltage[4]		1.14 to 1.575	V
	1.5 V DC supply voltage		1.425 to 1.575	V
	1.8 V DC supply voltage		1.7 to 1.9	V
	2.5 V DC supply voltage		2.3 to 2.7	V
	3.0 V DC supply voltage[7]		2.7 to 3.6	V
	3.3 V DC supply voltage		3.0 to 3.6	V
	LVDS differential I/O		2.375 to 2.625	V
	LVPECL differential I/O		3.0 to 3.6	V

Notes:

1. *All parameters representing voltages are measured with respect to GND unless otherwise specified.*
2. *Default Junction Temperature Range in the Libero SoC software is set from 0°C to +70°C for commercial, and -40°C to +85°C for industrial. To ensure targeted reliability standards are met across the full range of junction temperatures, Microsemi recommends using custom settings for temperature range before running timing and power analysis tools. For more information regarding custom settings, refer to the New Project Dialog Box in the Libero SoC Online Help.*
3. *For A3P250 and A3P1000*
4. *For A3PE600L and A3PE3000L devices only, operating at VCCI ≥ VCC.*
5. *See the "Pin Descriptions and Packaging" section on page 3-1 for instructions and recommendations on tie-off and supply grouping.*
6. *The ranges given here are for power supplies only. The recommended input voltage ranges specific to each I/O standard are given in Table 2-25 on page 2-22. VCCI should be at the same voltage within a given I/O bank.*
7. *3.3 V wide range is compliant to the JESD8-B specification and supports 3.0 V VCCI operation.*
8. *To ensure targeted reliability standards are met across ambient and junction operating temperatures, Microsemi recommends that the user follow best design practices using Microsemi's timing and power simulation tools.*

Calculating Power Dissipation

Quiescent Supply Current

Table 2-8 • Power Supply State Per Mode

	Power Supply Configurations				
Modes/Power Supplies	**VCC**	**VCCPLL**	**VCCI**	**VJTAG**	**VPUMP**
Flash*Freeze	On	On	On	On	On/off/floating
Sleep	Off	Off	On	Off	Off
Shutdown	Off	Off	Off	Off	Off
Static and Active	On	On	On	On	On/off/floating

Table 2-9 • Quiescent Supply Current (IDD) Characteristics, Flash*Freeze Mode*

	Core Voltage	A3PE600L	A3PE3000L	Units
Nominal (25°C)	1.2 V	0.55	2.75	mA
	1.5 V	0.83	4.2	mA
Typical maximum (25ºC)	1.2 V	9	17	mA
	1.5 V	12	20	mA
Military maximum (125ºC)	1.2 V	65	165	mA
	1.5 V	85	185	mA

Note: *IDD includes VCC, VPUMP, VCCI, VJTAG, and VCCPLL currents. Values do not include I/O static contribution (PDC6 and PDC7).*

Table 2-10 • Quiescent Supply Current (IDD) Characteristics, Sleep Mode (VCC = 0 V)*

	Core Voltage	A3PE600L	A3PE3000L	Units
VCCI / VJTAG = 1.2 V (per bank) Typical (25°C)	1.2 V	1.7	1.7	µA
VCCI / VJTAG = 1.5 V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.8	1.8	µA
VCCI / VJTAG = 1.8 V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.9	1.9	µA
VCCI / VJTAG = 2.5 V (per bank) Typical (25°C)	1.2 V / 1.5 V	2.2	2.2	µA
VCCI / VJTAG = 3.3 V (per bank) Typical (25°C)	1.2 V / 1.5 V	2.5	2.5	µA

Note: **IDD = N_{BANKS} × ICCI. Values do not include I/O static contribution, which is shown in Table 2-22 on page 2-14 (PDC6 and PDC7).*

Table 2-11 • Quiescent Supply Current (IDD) Characteristics, Shutdown Mode*

	Core Voltage	A3P250	A3P1000	A3PE600L	A3PE3000L	Units
Nominal (25°C)	1.2 V / 1.5 V	N/A		0		µA
Military (125ºC)	1.2 V / 1.5 V	N/A		0		µA

Note: **This is applicable to A3PE600L and A3PE3000L only for cold-sparable I/O devices. Not available on A3P250 or A3P1000.*

User I/O Characteristics

Timing Model

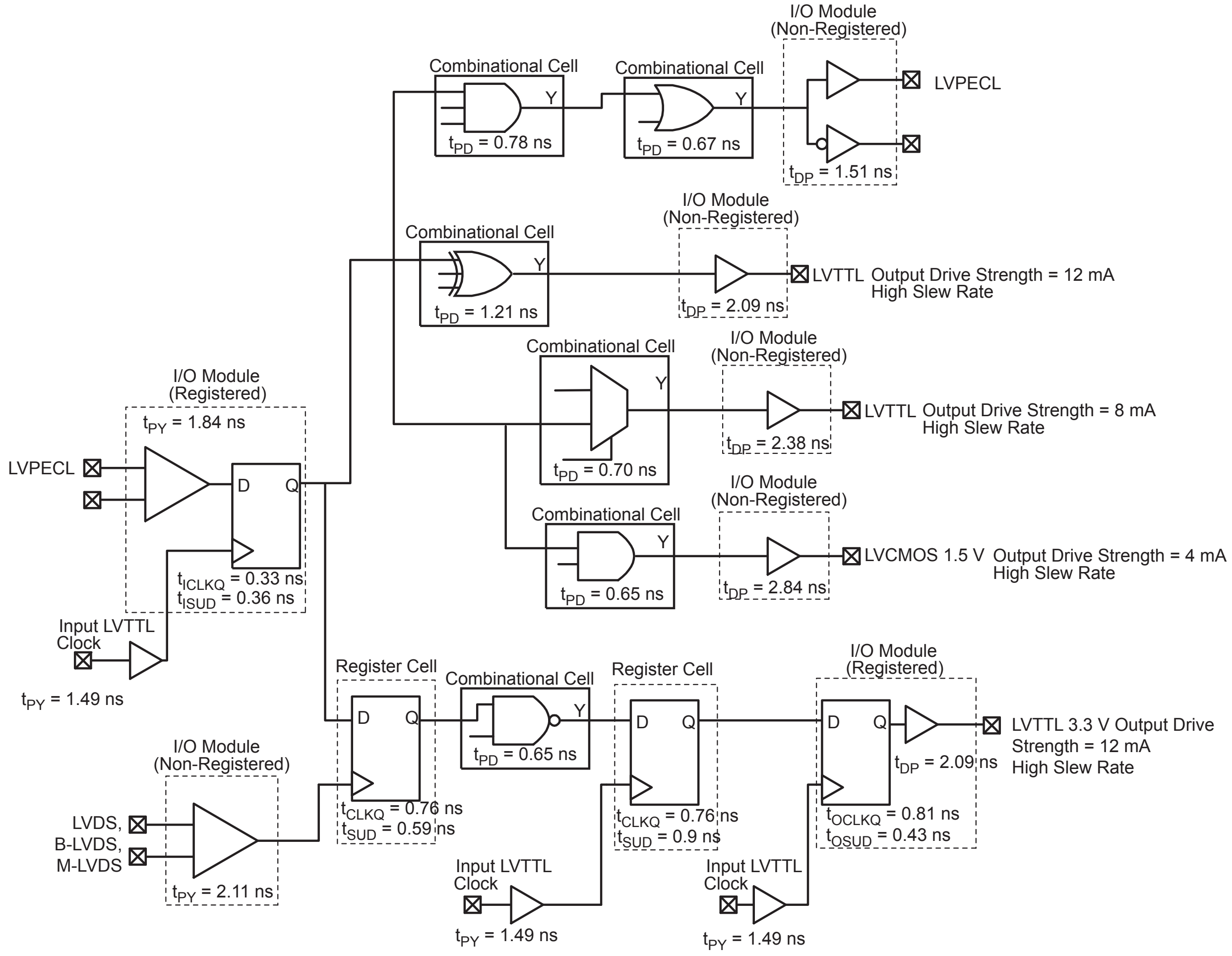


Figure 2-3 • **Timing Model**
Operating Conditions: –1 Speed, Military Temperature Range (T_J = 125°C), Worst-Case VCC = 1.14 V (example for A3PE3000L and A3PE600L)

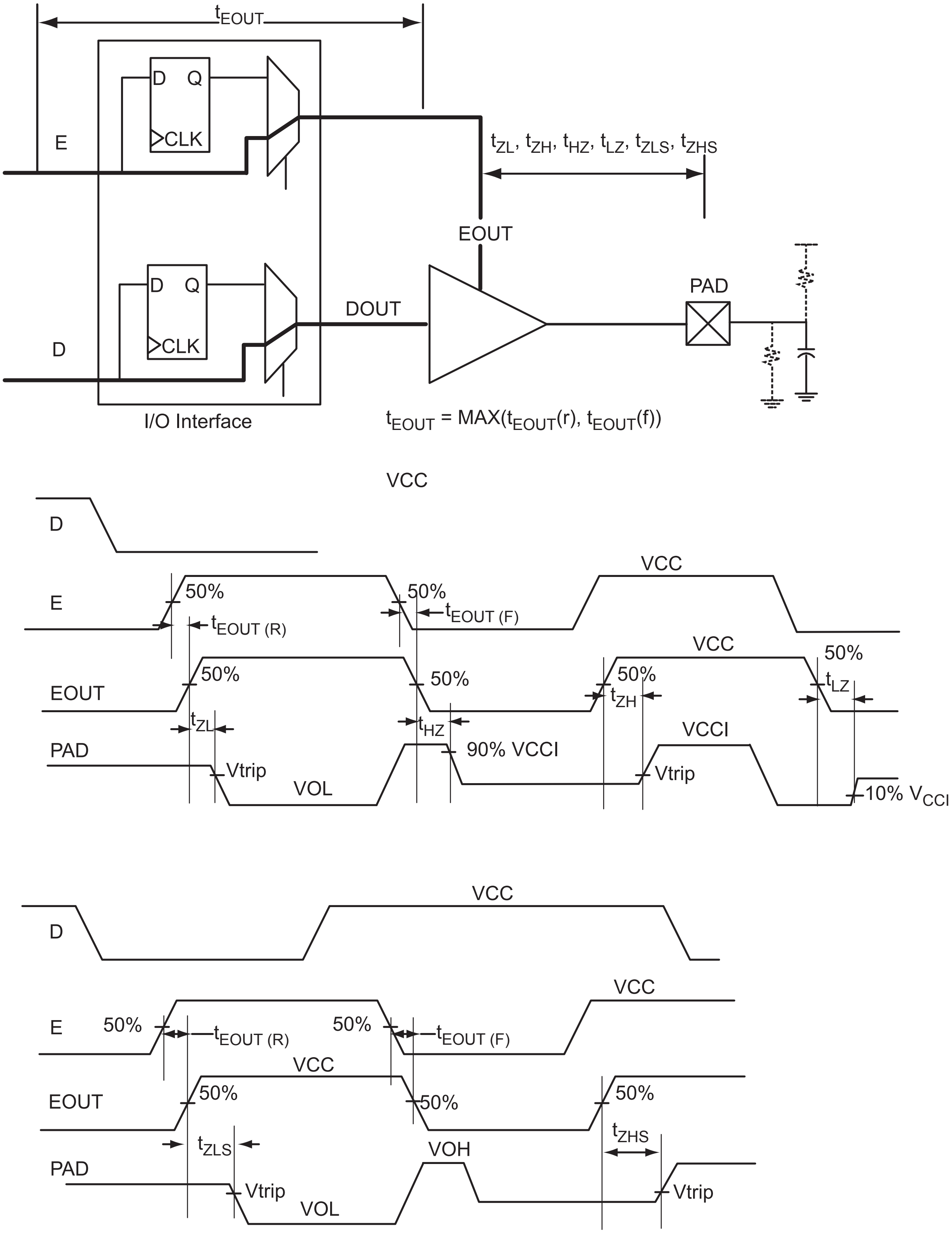


Figure 2-6 • **Tristate Output Buffer Timing Model and Delays (example)**

Timing Characteristics

1.2 V DC Core Voltage

Table 2-74 • **2.5 V LVCMOS Low Slew**
Military-Case Conditions: T_J = 125°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.80	6.87	0.05	2.04	2.56	0.52	6.99	5.83	2.70	2.19	9.20	8.03	ns
	–1	0.68	5.84	0.05	1.73	2.17	0.44	5.95	4.96	2.29	1.86	7.82	6.83	ns
8 mA	Std.	0.80	5.62	0.05	2.04	2.56	0.52	5.72	4.94	3.08	2.90	7.92	7.14	ns
	–1	0.68	4.78	0.05	1.73	2.17	044	4.86	4.20	2.62	2.47	6.74	6.08	ns
12 mA	Std.	0.80	4.73	0.05	2.04	2.56	0.52	4.81	4.30	3.34	3.38	7.01	6.50	ns
	–1	0.68	4.02	0.05	1.73	2.17	0.44	4.09	3.65	2.84	2.87	5.97	5.53	ns
16 mA	Std.	0.80	4.46	0.05	2.04	2.56	0.52	4.53	4.16	3.39	3.50	6.74	6.36	ns
	–1	0.68	3.79	0.05	1.73	2.17	0.44	3.86	3.54	2.89	2.98	5.73	5.41	ns
24 mA	Std.	0.80	4.34	0.05	2.04	2.56	0.52	4.41	4.17	3.47	3.96	6.62	6.38	ns
	–1	0.68	3.69	0.05	1.73	2.17	0.44	3.75	3.55	2.95	3.96	5.63	5.43	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-75 • **2.5 V LVCMOS High Slew**
Military-Case Conditions: T_J = 125°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.80	3.51	0.05	2.04	2.56	0.52	3.56	3.13	2.70	2.27	5.77	5.33	ns
	–1	0.68	2.98	0.05	1.73	2.17	0.44	3.03	2.66	2.29	1.93	4.91	4.53	ns
8 mA	Std.	0.80	2.87	0.05	2.04	2.56	0.52	2.92	2.40	3.08	3.01	5.12	4.61	ns
	–1	0.68	2.44	0.05	1.73	2.17	0.44	2.48	2.05	2.62	2.56	4.36	3.92	ns
12 mA	Std.	0.80	2.50	0.05	2.04	2.56	0.52	2.53	2.05	3.34	3.47	4.74	4.25	ns
	–1	0.68	2.12	0.05	1.73	2.17	0.44	2.15	1.74	2.84	2.95	4.03	3.62	ns
16 mA	Std.	0.80	2.43	0.05	2.04	2.56	0.52	2.47	1.98	3.39	3.59	4.67	4.19	ns
	–1	0.68	2.07	0.05	1.73	2.17	0.44	2.10	1.69	2.89	3.06	3.97	3.56	ns
24 mA	Std.	0.80	2.44	0.05	2.04	2.56	0.52	2.48	1.90	3.47	4.08	4.68	4.10	ns
	–1	0.68	2.08	0.05	1.73	2.17	0.44	2.11	1.61	2.95	3.47	3.98	3.49	ns

Notes:

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.*

Voltage-Referenced I/O Characteristics

3.3 V GTL

Gunning Transceiver Logic is a high-speed bus standard (JESD8-3). It provides a differential amplifier input buffer and an open-drain output buffer. The V_{CCI} pin should be connected to 3.3 V.

***Table 2-120* • Minimum and Maximum DC Input and Output Levels**

3.3 V GTL	VIL		VIH		VOL	VOH	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}[1]	I_{IH}[2]
Drive Strength	**Min. V**	**Max. V**	**Min. V**	**Max. V**	**Max. V**	**Min. V**	**mA**	**mA**	**Max. mA[3]**	**Max. mA[3]**	**µA[4]**	**µA[4]**
20 mA[5]	–0.3	VREF – 0.05	VREF + 0.05	3.6	0.4	–	20	20	268	181	15	15

Notes:

1. *I_{IL} is the input leakage current per I/O pin over recommended operating conditions where –0.3 V < VIN < VIL.*
2. *I_{IH} is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges.*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 125°C junction temperature.*
5. *Output drive strength is below JEDEC specification.*

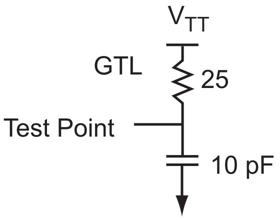


***Figure 2-15* • AC Loading**

***Table 2-121* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ.) (V)	VTT (typ.) (V)	C_{LOAD} (pF)
VREF – 0.05	VREF + 0.05	0.8	0.8	1.2	10

Note: **Measuring point = V_{trip}. See* Table 2-29 on page 2-25 *for a complete table of trip points.*

Timing Characteristics

***Table 2-122* • 3.3 V GTL**
Military-Case Conditions: T_J = 125°C, Worst-Case VCC = 1.14 V,
Worst-Case VCCI = 3.0 V, VREF = 0.8 V
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.80	2.05	0.05	2.34	0.52	2.01	2.05	–	–	4.22	4.26	ns
–1	0.68	1.75	0.05	1.99	0.44	1.71	1.75	–	–	3.59	3.62	ns

Note: *For specific junction temperature and voltage supply levels, refer to* Table 2-6 on page 2-6 *for derating values.*

B-LVDS/M-LVDS

Bus LVDS (B-LVDS) and Multipoint LVDS (M-LVDS) specifications extend the existing LVDS standard to high-performance multipoint bus applications. Multidrop and multipoint bus configurations may contain any combination of drivers, receivers, and transceivers. Microsemi LVDS drivers provide the higher drive current required by B-LVDS and M-LVDS to accommodate the loading. The drivers require series terminations for better signal quality and to control voltage swing. Termination is also required at both ends of the bus since the driver can be located anywhere on the bus. These configurations can be implemented using the TRIBUF_LVDS and BIBUF_LVDS macros along with appropriate terminations. Multipoint designs using Microsemi LVDS macros can achieve up to 200 MHz with a maximum of 20 loads. A sample application is given in Figure 2-26. The input and output buffer delays are available in the LVDS section in Table 2-160 on page 2-86.

Example: For a bus consisting of 20 equidistant loads, the following terminations provide the required differential voltage, in worst-case Industrial operating conditions, at the farthest receiver: R_S = 60 Ω and R_T = 70 Ω, given Z_0 = 50 Ω (2") and Z_{stub} = 50 Ω (~1.5").

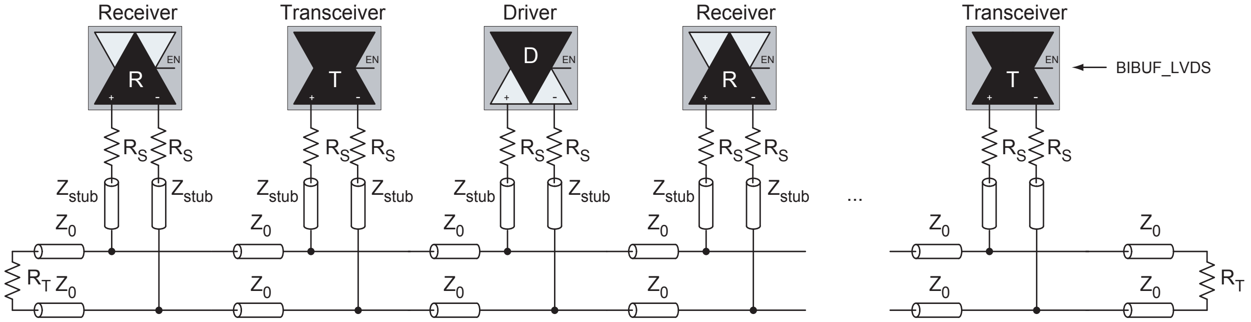


Figure 2-26 • **B-LVDS/M-LVDS Multipoint Application Using LVDS I/O Buffers**

Input Register

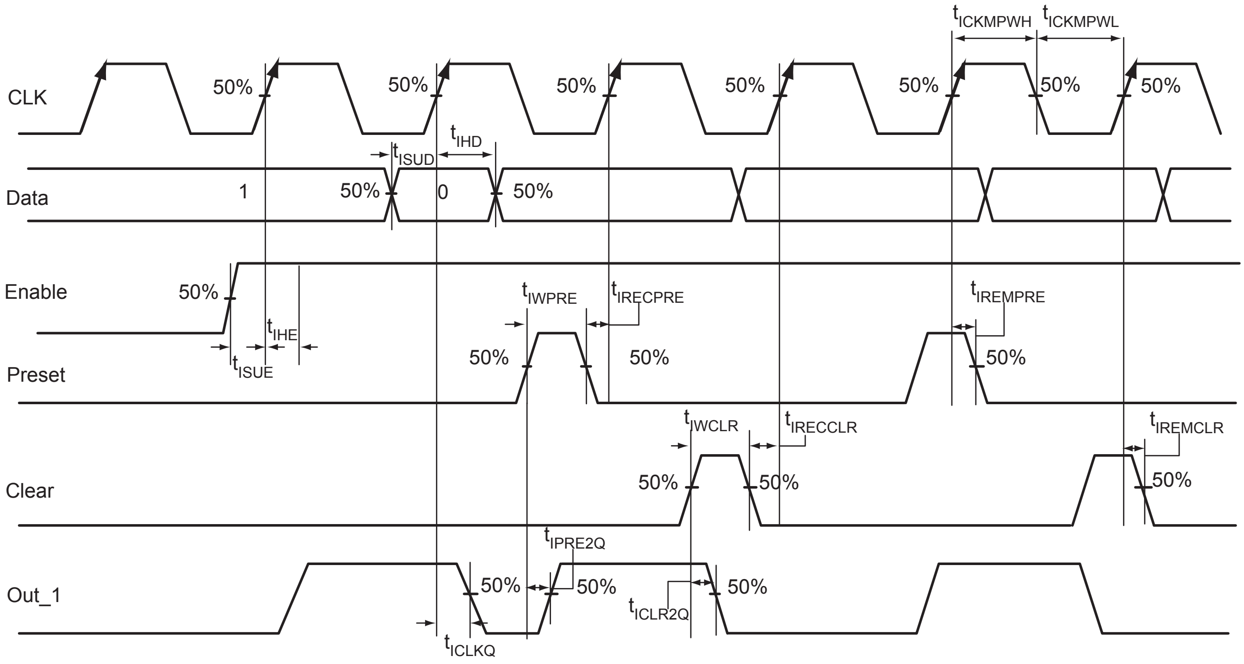


Figure 2-30 • **Input Register Timing Diagram**

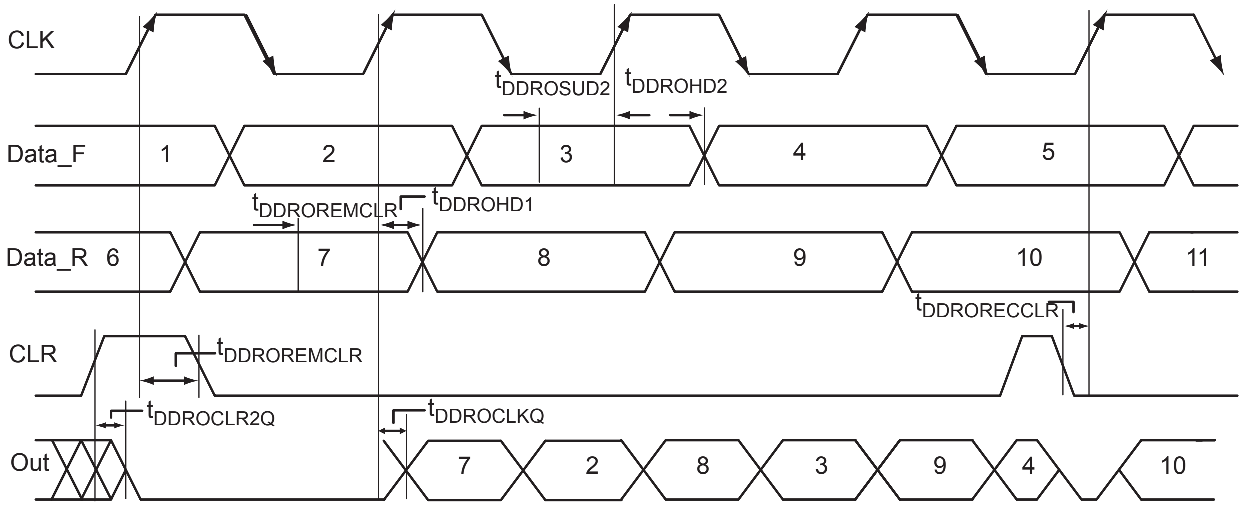


Figure 2-36 • **Output DDR Timing Diagram**

Timing Characteristics

Table 2-186 • **Output DDR Propagation Delays**
Military-Case Conditions: T_J = 125°C, Worst-Case VCC = 1.14 V for A3PE600L and A3PE3000L

Parameter	Description	–1	Std.	Units
$t_{DDROCLKQ}$	Clock-to-Out of DDR for Output DDR	0.97	1.14	ns
$t_{DDRISUD1}$	Data_F Data Setup for Output DDR	0.52	0.62	ns
$t_{DDROSUD2}$	Data_R Data Setup for Output DDR	0.52	0.62	ns
$t_{DDROHD1}$	Data_F Data Hold for Output DDR	0.00	0.00	ns
$t_{DDROHD2}$	Data_R Data Hold for Output DDR	0.00	0.00	ns
$t_{DDROCLR2Q}$	Asynchronous Clear-to-Out for Output DDR	1.11	1.30	ns
$t_{DDROREMCLR}$	Asynchronous Clear Removal Time for Output DDR	0.00	0.00	ns
$t_{DDRORECCLR}$	Asynchronous Clear Recovery Time for Output DDR	0.31	0.36	ns
$t_{DDROWCLR1}$	Asynchronous Clear Minimum Pulse Width for Output DDR	0.19	0.22	ns
$t_{DDROCKMPWH}$	Clock Minimum Pulse Width HIGH for the Output DDR	0.31	0.36	ns
$t_{DDROCKMPWL}$	Clock Minimum Pulse Width LOW for the Output DDR	0.28	0.32	ns
$F_{DDROMAX}$	Maximum Frequency for the Output DDR	160	160	MHz

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-187 • **Output DDR Propagation Delays**
Military-Case Conditions: T_J = 125°C, VCC = 1.425 V for A3PE600L and A3PE3000L

Parameter	Description	–1	Std.	Units
$t_{DDROCLKQ}$	Clock-to-Out of DDR for Output DDR	0.74	0.87	ns
$t_{DDRISUD1}$	Data_F Data Setup for Output DDR	0.40	0.47	ns
$t_{DDROSUD2}$	Data_R Data Setup for Output DDR	0.40	0.47	ns
$t_{DDROHD1}$	Data_F Data Hold for Output DDR	0.00	0.00	ns
$t_{DDROHD2}$	Data_R Data Hold for Output DDR	0.00	0.00	ns
$t_{DDROCLR2Q}$	Asynchronous Clear-to-Out for Output DDR	0.85	1.00	ns
$t_{DDROREMCLR}$	Asynchronous Clear Removal Time for Output DDR	0.00	0.00	ns
$t_{DDRORECCLR}$	Asynchronous Clear Recovery Time for Output DDR	0.24	0.28	ns
$t_{DDROWCLR1}$	Asynchronous Clear Minimum Pulse Width for Output DDR	0.19	0.22	ns
$t_{DDROCKMPWH}$	Clock Minimum Pulse Width HIGH for the Output DDR	0.31	0.36	ns
$t_{DDROCKMPWL}$	Clock Minimum Pulse Width LOW for the Output DDR	0.28	0.32	ns
$F_{DDROMAX}$	Maximum Frequency for the Output DDR	250	250	MHz

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-188 • **Output DDR Propagation Delays**
Military-Case Conditions: T_J = 125°C, Worst-Case VCC = 1.425 V for A3P250 and A3P1000

Parameter	Description	–1	Std.	Units
$t_{DDROCLKQ}$	Clock-to-Out of DDR for Output DDR	0.84	0.99	ns
$t_{DDRISUD1}$	Data_F Data Setup for Output DDR	0.46	0.54	ns
$t_{DDROSUD2}$	Data_R Data Setup for Output DDR	0.46	0.54	ns
$t_{DDROHD1}$	Data_F Data Hold for Output DDR	0.00	0.00	ns
$t_{DDROHD2}$	Data_R Data Hold for Output DDR	0.00	0.00	ns
$t_{DDROCLR2Q}$	Asynchronous Clear-to-Out for Output DDR	0.96	1.13	ns
$t_{DDROREMCLR}$	Asynchronous Clear Removal Time for Output DDR	0.00	0.00	ns
$t_{DDRORECCLR}$	Asynchronous Clear Recovery Time for Output DDR	0.27	0.31	ns
$t_{DDROWCLR1}$	Asynchronous Clear Minimum Pulse Width for Output DDR	0.25	0.30	ns
$t_{DDROCKMPWH}$	Clock Minimum Pulse Width HIGH for the Output DDR	0.41	0.48	ns
$t_{DDROCKMPWL}$	Clock Minimum Pulse Width LOW for the Output DDR	0.37	0.43	ns
$F_{DDROMAX}$	Maximum Frequency for the Output DDR	309	263	MHz

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-6 for derating values.

Table 2-191 • Combinatorial Cell Propagation Delays
Military-Case Conditions: T_J = 125°C, Worst-Case VCC = 1.425 V for A3P250 and A3P1000

Combinatorial Cell	Equation	Parameter	–1	Std.	Units
INV	Y = !A	t_{PD}	0.48	0.57	ns
AND2	Y = A · B	t_{PD}	0.57	0.67	ns
NAND2	Y = !(A · B)	t_{PD}	0.57	0.67	ns
OR2	Y = A + B	t_{PD}	0.59	0.69	ns
NOR2	Y = !(A + B)	t_{PD}	0.59	0.69	ns
XOR2	$Y = A \oplus B$	t_{PD}	0.89	1.04	ns
MAJ3	Y = MAJ(A , B, C)	t_{PD}	0.84	0.99	ns
XOR3	$Y = A \oplus B \oplus C$	t_{PD}	1.05	1.24	ns
MUX2	Y = A !S + B S	t_{PD}	0.61	0.72	ns
AND3	Y = A · B · C	t_{PD}	0.68	0.79	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-6 for derating values.

1.5 V DC Core Voltage

Table 2-197 • A3PE600L Global Resource
Military-Case Conditions: T_J = 125°C, VCC = 1.425 V

Parameter	Description	–1		Std.		Units
		Min.[1]	Max.[2]	Min.[1]	Max.[2]	
t_{RCKL}	Input Low Delay for Global Clock	0.82	1.07	0.97	1.26	ns
t_{RCKH}	Input High Delay for Global Clock	0.81	1.10	0.95	1.30	ns
$t_{RCKMPWH}$	Minimum Pulse Width High for Global Clock					ns
$t_{RCKMPWL}$	Minimum Pulse Width Low for Global Clock					ns
t_{RCKSW}	Maximum Skew for Global Clock		0.30		0.35	ns
F_{RMAX}	Maximum Frequency for Global Clock					MHz

Notes:

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.*

Table 2-198 • A3PE3000L Global Resource
Military-Case Conditions: T_J = 125°C, VCC = 1.425 V

Parameter	Description	–1		Std.		Units
		Min.[1]	Max.[2]	Min.[1]	Max.[2]	
t_{RCKL}	Input Low Delay for Global Clock	1.62	1.87	1.90	2.20	ns
t_{RCKH}	Input High Delay for Global Clock	1.61	1.90	1.89	2.24	ns
$t_{RCKMPWH}$	Minimum Pulse Width High for Global Clock					ns
$t_{RCKMPWL}$	Minimum Pulse Width Low for Global Clock					ns
t_{RCKSW}	Maximum Skew for Global Clock		0.30		0.35	ns
F_{RMAX}	Maximum Frequency for Global Clock					MHz

Notes:

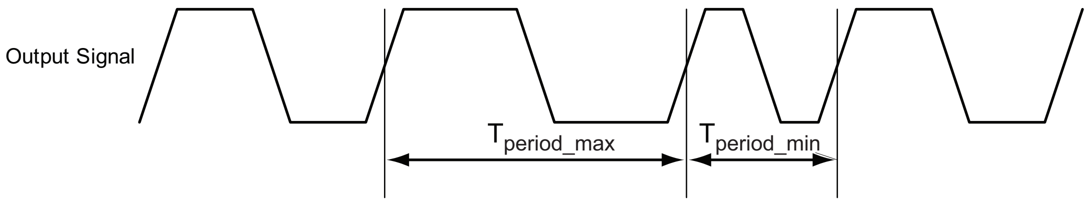
1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.*

Table 2-202 • **Military ProASIC3/EL CCC/PLL Specification For Devices Operating at 1.5 V DC Core Voltage**

Parameter	Min.	Typ.	Max.	Units
Clock Conditioning Circuitry Input Frequency f_{IN_CCC}	1.5		350	MHz
Clock Conditioning Circuitry Output Frequency f_{OUT_CCC}	0.75		350	MHz
Delay Increments in Programmable Delay Blocks [1, 2,3]		160		ps
Number of Programmable Values in Each Programmable Delay Block			32	
Serial Clock (SCLK) for Dynamic PLL[4]			110	MHz
Input cycle-to-cycle jitter (peak magnitude)			1.5	ns
Acquisition Time				
LockControl = 0			300	µs
LockControl = 1			6.0	ms
Tracking Jitter[5]				
LockControl = 0			1.6	ns
LockControl = 1			0.8	ns
Output Duty Cycle	48.5		51.5	%
Delay Range in Block: Programmable Delay 1 [1,2]	0.6		5.56	ns
Delay Range in Block: Programmable Delay 2 [1,2]	0.025		5.56	ns
Delay Range in Block: Fixed Delay [1,2]		2.2		ns
CCC Output Peak-to-Peak Period Jitter F_{CCC_OUT}	Max. Peak-to-Peak Period Jitter [6,7]			
	SSO ≤ 2	SSO ≤ 4	SSO ≤ 8	SSO ≤ 16
0.75 MHz to 50 MHz	0.50%	0.50%	0.70%	1.00%
50 MHz to 250 MHz	1.00%	3.00%	5.00%	9.00%
250 MHz to 350 MHz	2.50%	4.00%	6.00%	12.00%

Notes:

1. *This delay is a function of voltage and temperature. See Table 2-6 on page 2-6 for deratings.*
2. *T_J = 25°C, VCC = 1.5 V.*
3. *When the CCC/PLL core is generated by Mircosemi core generator software, not all delay values of the specified delay increments are available. Refer to the Libero online help associated with the core for more information.*
4. *Maximum value obtained for a -1 speed grade device in worst-case military conditions. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.*
5. *Tracking jitter is defined as the variation in clock edge position of PLL outputs with reference to PLL input clock edge. Tracking jitter does not measure the variation in PLL output period, which is covered by period jitter parameter.*
6. *Measurements done with LVTTL 3.3 V, 8 mA I/O drive strength and high slew rate. VCC/VCCPLL = 1.425 V, VQ/PQ/TQ type of packages, 20 pF load.*
7. *Switching I/Os are placed outside of the PLL bank.*



Note: *Peak-to-peak jitter measurements are defined by* $T_{peak\text{-}to\text{-}peak} = T_{period\_max} - T_{period\_min}$.

Figure 2-42 • **Peak-to-Peak Jitter Definition**

VCOMPLA/B/C/D/E/F PLL Ground

Ground to analog PLL power supplies. When the PLLs are not used, the Microsemi Designer place-and-route tool automatically disables the unused PLLs to lower power consumption. The user should tie unused VCCPLx and VCOMPLx pins to ground.

- There is one VCOMPLF pin on A3P250 and A3P1000 devices.
- There are six VCOMPL pins (PLL ground) on A3PE600L and A3PE3000L devices.

VJTAG JTAG Supply Voltage

Military ProASIC3/EL devices have a separate bank for the dedicated JTAG pins. The JTAG pins can be run at any voltage from 1.5 V to 3.3 V (nominal). Isolating the JTAG power supply in a separate I/O bank gives greater flexibility in supply selection and simplifies power supply and PCB design. If the JTAG interface is neither used nor planned for use, the VJTAG pin together with the TRST pin could be tied to GND. It should be noted that VCC is required to be powered for JTAG operation; VJTAG alone is insufficient. If a device is in a JTAG chain of interconnected boards, the board containing the device can be powered down, provided both VJTAG and VCC to the part remain powered; otherwise, JTAG signals will not be able to transition the device, even in bypass mode.

Microsemi recommends that VPUMP and VJTAG power supplies be kept separate with independent filtering capacitors rather than supplying them from a common rail.

VPUMP Programming Supply Voltage

A3P250 and A3P1000 devices support single-voltage ISP of the configuration flash and FlashROM. For programming, VPUMP should be 3.3 V nominal. During normal device operation, VPUMP can be left floating or can be tied (pulled up) to any voltage between 0 V and the VPUMP maximum. Programming power supply voltage (VPUMP) range is listed in Table 2-2 on page 2-2.

When the VPUMP pin is tied to ground, it will shut off the charge pump circuitry, resulting in no sources of oscillation from the charge pump circuitry.

For proper programming, 0.01 µF and 0.33 µF capacitors (both rated at 16 V) are to be connected in parallel across VPUMP and GND, and positioned as close to the FPGA pins as possible.

Microsemi recommends that VPUMP and VJTAG power supplies be kept separate with independent filtering capacitors rather than supplying them from a common rail.

User-Defined Supply Pins

VREF I/O Voltage Reference

Reference voltage for I/O minibanks in A3PE600L and A3PE3000L devices. VREF pins are configured by the user from regular I/Os, and any I/O in a bank, except JTAG I/Os, can be designated the voltage reference I/O. Only certain I/O standards require a voltage reference—HSTL (I) and (II), SSTL2 (I) and (II), SSTL3 (I) and (II), and GTL/GTL+. One VREF pin can support the number of I/Os available in its minibank.

User Pins

I/O User Input/Output

The I/O pin functions as an input, output, tristate, or bidirectional buffer. Input and output signal levels are compatible with the I/O standard selected.

During programming, I/Os become tristated and weakly pulled up to VCCI. With VCCI, VMV, and VCC supplies continuously powered up, when the device transitions from programming to operating mode, the I/Os are instantly configured to the desired user configuration.

Unused I/Os are configured as follows:

- Output buffer is disabled (with tristate value of high impedance)
- Input buffer is disabled (with tristate value of high impedance)
- Weak pull-up is programmed

FG144	
Pin Number	**A3P1000 Function**
A1	GNDQ
A2	VMV0
A3	GAB0/IO02RSB0
A4	GAB1/IO03RSB0
A5	IO10RSB0
A6	GND
A7	IO44RSB0
A8	VCC
A9	IO69RSB0
A10	GBA0/IO76RSB0
A11	GBA1/IO77RSB0
A12	GNDQ
B1	GAB2/IO224PDB3
B2	GND
B3	GAA0/IO00RSB0
B4	GAA1/IO01RSB0
B5	IO13RSB0
B6	IO26RSB0
B7	IO35RSB0
B8	IO60RSB0
B9	GBB0/IO74RSB0
B10	GBB1/IO75RSB0
B11	GND
B12	VMV1
C1	IO224NDB3
C2	GFA2/IO206PPB3
C3	GAC2/IO223PDB3
C4	VCC
C5	IO16RSB0
C6	IO29RSB0
C7	IO32RSB0
C8	IO63RSB0
C9	IO66RSB0
C10	GBA2/IO78PDB1
C11	IO78NDB1
C12	GBC2/IO80PPB1

FG144	
Pin Number	**A3P1000 Function**
D1	IO213PDB3
D2	IO213NDB3
D3	IO223NDB3
D4	GAA2/IO225PPB3
D5	GAC0/IO04RSB0
D6	GAC1/IO05RSB0
D7	GBC0/IO72RSB0
D8	GBC1/IO73RSB0
D9	GBB2/IO79PDB1
D10	IO79NDB1
D11	IO80NPB1
D12	GCB1/IO92PPB1
E1	VCC
E2	GFC0/IO209NDB3
E3	GFC1/IO209PDB3
E4	VCCIB3
E5	IO225NPB3
E6	VCCIB0
E7	VCCIB0
E8	GCC1/IO91PDB1
E9	VCCIB1
E10	VCC
E11	GCA0/IO93NDB1
E12	IO94NDB1
F1	GFB0/IO208NPB3
F2	VCOMPLF
F3	GFB1/IO208PPB3
F4	IO206NPB3
F5	GND
F6	GND
F7	GND
F8	GCC0/IO91NDB1
F9	GCB0/IO92NPB1
F10	GND
F11	GCA1/IO93PDB1
F12	GCA2/IO94PDB1

FG144	
Pin Number	**A3P1000 Function**
G1	GFA1/IO207PPB3
G2	GND
G3	VCCPLF
G4	GFA0/IO207NPB3
G5	GND
G6	GND
G7	GND
G8	GDC1/IO111PPB1
G9	IO96NDB1
G10	GCC2/IO96PDB1
G11	IO95NDB1
G12	GCB2/IO95PDB1
H1	VCC
H2	GFB2/IO205PDB3
H3	GFC2/IO204PSB3
H4	GEC1/IO190PDB3
H5	VCC
H6	IO105PDB1
H7	IO105NDB1
H8	GDB2/IO115RSB2
H9	GDC0/IO111NPB1
H10	VCCIB1
H11	IO101PSB1
H12	VCC
J1	GEB1/IO189PDB3
J2	IO205NDB3
J3	VCCIB3
J4	GEC0/IO190NDB3
J5	IO160RSB2
J6	IO157RSB2
J7	VCC
J8	TCK
J9	GDA2/IO114RSB2
J10	TDO
J11	GDA1/IO113PDB1
J12	GDB1/IO112PDB1

FG256	
Pin Number	**A3P1000 Function**
A1	GND
A2	GAA0/IO00RSB0
A3	GAA1/IO01RSB0
A4	GAB0/IO02RSB0
A5	IO16RSB0
A6	IO22RSB0
A7	IO28RSB0
A8	IO35RSB0
A9	IO45RSB0
A10	IO50RSB0
A11	IO55RSB0
A12	IO61RSB0
A13	GBB1/IO75RSB0
A14	GBA0/IO76RSB0
A15	GBA1/IO77RSB0
A16	GND
B1	GAB2/IO224PDB3
B2	GAA2/IO225PDB3
B3	GNDQ
B4	GAB1/IO03RSB0
B5	IO17RSB0
B6	IO21RSB0
B7	IO27RSB0
B8	IO34RSB0
B9	IO44RSB0
B10	IO51RSB0
B11	IO57RSB0
B12	GBC1/IO73RSB0
B13	GBB0/IO74RSB0
B14	IO71RSB0
B15	GBA2/IO78PDB1
B16	IO81PDB1
C1	IO224NDB3
C2	IO225NDB3
C3	VMV3
C4	IO11RSB0
C5	GAC0/IO04RSB0
C6	GAC1/IO05RSB0
C7	IO25RSB0
C8	IO36RSB0
C9	IO42RSB0
C10	IO49RSB0
C11	IO56RSB0
C12	GBC0/IO72RSB0
C13	IO62RSB0
C14	VMV0
C15	IO78NDB1
C16	IO81NDB1
D1	IO222NDB3
D2	IO222PDB3
D3	GAC2/IO223PDB3
D4	IO223NDB3
D5	GNDQ
D6	IO23RSB0
D7	IO29RSB0
D8	IO33RSB0
D9	IO46RSB0
D10	IO52RSB0
D11	IO60RSB0
D12	GNDQ
D13	IO80NDB1
D14	GBB2/IO79PDB1
D15	IO79NDB1
D16	IO82NSB1
E1	IO217PDB3
E2	IO218PDB3
E3	IO221NDB3
E4	IO221PDB3
E5	VMV0
E6	VCCIB0
E7	VCCIB0
E8	IO38RSB0
E9	IO47RSB0
E10	VCCIB0
E11	VCCIB0
E12	VMV1
E13	GBC2/IO80PDB1
E14	IO83PPB1
E15	IO86PPB1
E16	IO87PDB1
F1	IO217NDB3
F2	IO218NDB3
F3	IO216PDB3
F4	IO216NDB3
F5	VCCIB3
F6	GND
F7	VCC
F8	VCC
F9	VCC
F10	VCC
F11	GND
F12	VCCIB1
F13	IO83NPB1
F14	IO86NPB1
F15	IO90PPB1
F16	IO87NDB1
G1	IO210PSB3
G2	IO213NDB3
G3	IO213PDB3
G4	GFC1/IO209PPB3
G5	VCCIB3
G6	VCC
G7	GND
G8	GND
G9	GND
G10	GND
G11	VCC
G12	VCCIB1
G13	GCC1/IO91PPB1
G14	IO90NPB1
G15	IO88PDB1
G16	IO88NDB1
H1	GFB0/IO208NPB3
H2	GFA0/IO207NDB3

FG484	
Pin Number	**A3P1000 Function**
A1	GND
A2	GND
A3	VCCIB0
A4	IO07RSB0
A5	IO09RSB0
A6	IO13RSB0
A7	IO18RSB0
A8	IO20RSB0
A9	IO26RSB0
A10	IO32RSB0
A11	IO40RSB0
A12	IO41RSB0
A13	IO53RSB0
A14	IO59RSB0
A15	IO64RSB0
A16	IO65RSB0
A17	IO67RSB0
A18	IO69RSB0
A19	NC
A20	VCCIB0
A21	GND
A22	GND
B1	GND
B2	VCCIB3
B3	NC
B4	IO06RSB0
B5	IO08RSB0
B6	IO12RSB0
B7	IO15RSB0
B8	IO19RSB0
B9	IO24RSB0
B10	IO31RSB0
B11	IO39RSB0
B12	IO48RSB0
B13	IO54RSB0
B14	IO58RSB0
B15	IO63RSB0
B16	IO66RSB0
B17	IO68RSB0
B18	IO70RSB0
B19	NC
B20	NC
B21	VCCIB1
B22	GND
C1	VCCIB3
C2	IO220PDB3
C3	NC
C4	NC
C5	GND
C6	IO10RSB0
C7	IO14RSB0
C8	VCC
C9	VCC
C10	IO30RSB0
C11	IO37RSB0
C12	IO43RSB0
C13	NC
C14	VCC
C15	VCC
C16	NC
C17	NC
C18	GND
C19	NC
C20	NC
C21	NC
C22	VCCIB1
D1	IO219PDB3
D2	IO220NDB3
D3	NC
D4	GND
D5	GAA0/IO00RSB0
D6	GAA1/IO01RSB0
D7	GAB0/IO02RSB0
D8	IO16RSB0
D9	IO22RSB0
D10	IO28RSB0
D11	IO35RSB0
D12	IO45RSB0
D13	IO50RSB0
D14	IO55RSB0
D15	IO61RSB0
D16	GBB1/IO75RSB0
D17	GBA0/IO76RSB0
D18	GBA1/IO77RSB0
D19	GND
D20	NC
D21	NC
D22	NC
E1	IO219NDB3
E2	NC
E3	GND
E4	GAB2/IO224PDB3
E5	GAA2/IO225PDB3
E6	GNDQ
E7	GAB1/IO03RSB0
E8	IO17RSB0
E9	IO21RSB0
E10	IO27RSB0
E11	IO34RSB0
E12	IO44RSB0
E13	IO51RSB0
E14	IO57RSB0
E15	GBC1/IO73RSB0
E16	GBB0/IO74RSB0
E17	IO71RSB0

FG484	
Pin Number	**A3PE3000L Function**
V3	GND
V4	GEA1/IO234PDB6V0
V5	GEA0/IO234NDB6V0
V6	GNDQ
V7	GEC2/IO231PDB5V4
V8	IO222NPB5V3
V9	IO204NDB5V1
V10	IO204PDB5V1
V11	IO195NDB5V0
V12	IO195PDB5V0
V13	IO178NDB4V3
V14	IO178PDB4V3
V15	IO155NDB4V0
V16	GDB2/IO155PDB4V0
V17	TDI
V18	GNDQ
V19	TDO
V20	GND
V21	IO146PDB3V4
V22	IO142NDB3V3
W1	IO239NDB6V0
W2	IO237PDB6V0
W3	IO230PSB5V4
W4	GND
W5	IO232NDB5V4
W6	FF/GEB2/IO232PDB5V4
W7	IO231NDB5V4
W8	IO214NDB5V2
W9	IO214PDB5V2
W10	IO200NDB5V0
W11	IO192NDB4V4
W12	IO184NDB4V3
W13	IO184PDB4V3
W14	IO156NDB4V0
W15	GDC2/IO156PDB4V0

FG484	
Pin Number	**A3PE3000L Function**
W16	IO154NDB4V0
W17	GDA2/IO154PDB4V0
W18	TMS
W19	GND
W20	IO150NDB3V4
W21	IO146NDB3V4
W22	IO148PPB3V4
Y1	VCCIB6
Y2	IO237NDB6V0
Y3	IO228NDB5V4
Y4	IO224NDB5V3
Y5	GND
Y6	IO220NDB5V3
Y7	IO220PDB5V3
Y8	VCC
Y9	VCC
Y10	IO200PDB5V0
Y11	IO192PDB4V4
Y12	IO188NPB4V4
Y13	IO187PSB4V4
Y14	VCC
Y15	VCC
Y16	IO164NDB4V1
Y17	IO164PDB4V1
Y18	GND
Y19	IO158PPB4V0
Y20	IO150PDB3V4
Y21	IO148NPB3V4
Y22	VCCIB3